

This listing of claims will replace all prior versions, and listings, of claims in the application.

**Listing of Claims:**

1. (Currently Amended) A chip scale package suitable for use in a radio frequency (RF) range electronic device comprising:

a leadframe including (1) a die attach pad located thereon for connection directly to a circuit board and (2) a plurality of wire bonding pads peripherally located thereon;

at least one aperture formed fully through the die attach to separate the die attach pad into different sections;

at least one die having a first surface and an opposing second surface and being mounted on a section of the die attach pad such that substantially the entire opposing second surface is in mated contact with the die attach pad, thereby forming a grounding path from said at least one die, though said section and to said circuit board;

~~at least one aperture formed in the die attach surface;~~

at least one bonding wire for electrically connecting the at least one die and at least one of the plurality of wire bonding pads; and

a mold compound, wherein said mold compound encapsulates the at least one die and the at least one bonding wire to form a chip scale package, and wherein the mold compound resides in the at least one aperture, ~~wherein the aperture is formed fully through the die attach pad.~~

2. (Canceled)

3. (Canceled)

4. (Previously Presented) The chip package of claim 1, wherein the aperture is formed using a full etch process.

5. (Original) The chip package of claim 1, wherein the shape of the aperture is one of the following: a rectangle, a square, an oval, a triangle, a circle, or a combination thereof.

6. (Original) The chip package of claim 1, wherein the chip package is a leadframe-based Chip Scale Package.

7. (Original) The chip package of claim 1, wherein the aperture includes a plurality of apertures formed around the at least one die.

8. (Previously Presented) The chip package of claim 7, wherein the at least one die comprises at least a first and a second die, and at least one of the plurality of apertures is disposed between the first die and the second die.

9. (Previously Canceled)

10. (Withdrawn) A method of providing a chip package, comprising the steps of:  
providing a leadframe including a die attach pad centrally located therein and a plurality of wire bonding pads peripherally located therein;

providing at least one aperture in the die attach pad;  
providing at least one die on the die attach pad;  
providing at least one bonding wire for electrically connecting the die and the wire bonding pads; and providing a mold compound for encapsulating the die and the bonding wire to form a chip package, wherein the mold compound is formed in the aperture.

11. (Withdrawn) The method of claim 10, wherein the step of providing the aperture includes:

forming the aperture fully through the die attach pad.

12. (Withdrawn) The method of claim 10, wherein the step of providing the aperture includes:

forming the aperture partially through the die attach pad.

13. (Withdrawn) The method of claim 10, wherein the step of providing the aperture includes:

forming the aperture through the die attach pad using a combination of a full etch process and a half etch process.

14. (Withdrawn) The method of claim 10, wherein the shape of the aperture is one of the following: a rectangle, a square, an oval, a triangle, a circle, or a combination thereof.

15. (Withdrawn) The method of claim 10, wherein the chip package is a leadframe-based Chip Scale Package.

16. (Withdrawn) The method of claim 10, wherein the aperture includes a plurality of apertures formed around the at least one die.

17. (Withdrawn) The method of claim 16, wherein the at least one die includes a plurality of dies, and at least one of the plurality of apertures is disposed between the plurality of dies.

18. (Withdrawn) The method of claim 10, wherein the aperture extends horizontally, vertically, or diagonally.

19. (New) A method for improving radio frequency grounding in a high dynamic range electronic device comprising operating a chip scale package at radio frequency (RF), said chip scale package comprising:

a leadframe including (1) a die attach pad located thereon for connection directly to a circuit board and (2) a plurality of wire bonding pads peripherally located thereon;

at least one aperture formed fully through the die attach to separate the die attach pad into different sections;

at least one die having a first surface and an opposing second surface and being mounted on a section of the die attach pad such that substantially the entire opposing second surface is in

mated contact with the die attach pad, thereby forming an RF grounding path from said at least one die, through said section, and into said circuit board;

at least one bonding wire for electrically connecting the at least one die and at least one of the plurality of wire bonding pads; and

a mold compound, wherein said mold compound encapsulates the at least one die and the at least one bonding wire to form a chip scale package, and wherein the mold compound resides in the at least one aperture.